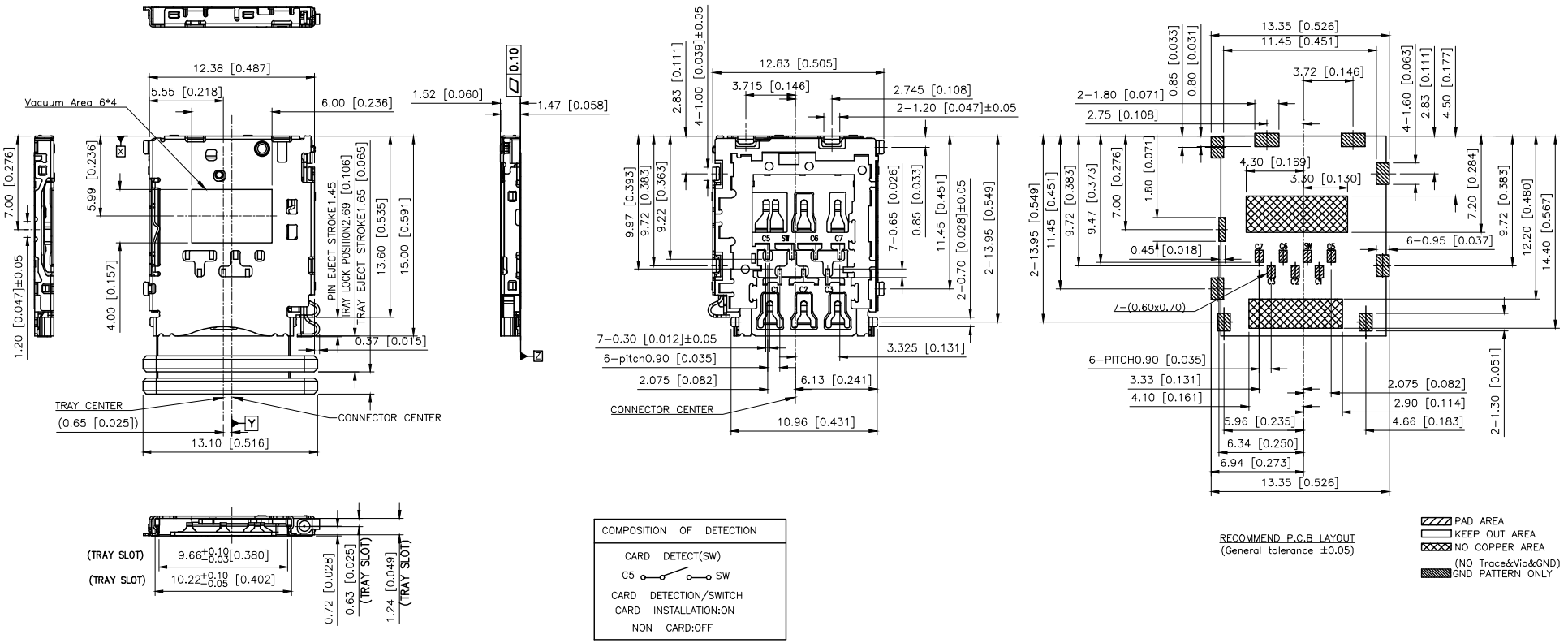
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A1	N/A			2025.10.14	
A2	ECN-P-2025122901			2025.12.29	



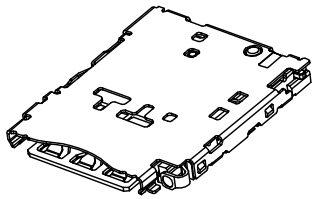
COMPOSITION OF DETECTION
CARD DETECT(SW)
C5 ○—○ SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON
NON CARD:OFF

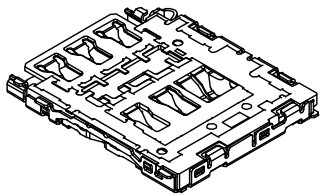
RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

PAD AREA
KEEP OUT AREA
NO COPPER AREA
(NO Trace&Via&GND)
GND PATTERN ONLY

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA





NOTE:
1. Material:
   1-1 Housing:High Temperature Thermoplastic(LCP S475)Color Black UL 94V-0
   1-2 Contact:Phosphor Bronze(C5210R-H,T=0.08±0.01mm)
   1-3 Cover: SUS304-H T=0.15±0.03mm
2. Plating:
   2-1 Contact terminal:
   Contact area: Gold 1u" Min.
   Solder area: Gold 0.8u" Min
   Underplating:Ni overall 50U" Min.
   2-2 Cover:
   Underplating: Ni overall 30U" Min.
   Solder area: Gold 0.8u" Min.
3. Specification:
   3-1. Current Rating :0.5A max.
   3-2. Contact Resistance:50 mohms max
   3-3. Insulation Resistance:1000 Mohms min./500VDC
   3-4. Dielectric Withstanding Voltage:500 V AC/1minute
   3-5. Operating Temperature:-40 to+85
   3-6. Mating Cycles:5000 Insertions
4.Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
5.Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderadility,If Use A Metal Mask Less Than 0.15mm Thick.

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuCES	

XKB Connection 星创

DESIGN		VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1131-18
APPROVED		SIZE: A4	DWG NO.:

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	1/1	A2